

Title (en)

Printed circuit substrate configuration and structure.

Title (de)

Substratkonfiguration und Struktur für gedruckte Schaltung.

Title (fr)

Configuration et structure de substrat de circuit imprimé.

Publication

**EP 0530096 B1 19950215 (EN)**

Application

**EP 92402337 A 19920825**

Priority

JP 24470391 A 19910829

Abstract (en)

[origin: EP0530096A1] The structure can be used with single or double-sided printed circuit boards (1) and comprises a centralized land (3) disposed on one side of the substrate, and a power source output terminal (3) and circuit terminals (5-7, 41) to be connected with the power source output terminal connected on the centralized land (2). The substrate reliability can be improved even for circuits submitted to under a high supply voltage and large currents, such as in a horizontal deflection output circuit. Also the line pattern can be reduced in usual applications, thereby minimizing heat generation and improving the reliability. <IMAGE>

IPC 1-7

**H05K 1/00**; **H05K 1/11**; **H05K 1/14**; **H05K 3/46**; **H04N 3/16**

IPC 8 full level

**H04N 3/16** (2006.01); **H05K 1/02** (2006.01); **H05K 1/11** (2006.01); **H05K 1/18** (2006.01)

CPC (source: EP KR)

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